PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2631686

SUBMISSION TYPE:	NEW ASSIGNMENT

NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CHI-CHENG TSAI	10/23/2013
HUNG-CHI WU	10/23/2013
TSUNG-CHUAN LEE	10/23/2013
CHUNG-HSIEN LIN	10/23/2013

RECEIVING PARTY DATA

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Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14067167

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ATTORNEY DOCKET NUMBER:	0941-2838PUS1

NAME OF SUBMITTER:	BRIAN OLIVE

OP $40.00 14067167

Signature:	/brian olive/
Date:	11/27/2013

Total Attachments: 2
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ASSIGNMENT

WHEREAS, Chi-Cheng TSAI, Hung-Chi WU, Tsung-Chuan LEE, and Chung-Hsien LIN hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **MECHANISMS FOR PERFORMING A PHOTOLITHOGRAPHY PROCESS**

Filed: October 30, 2013	Serial No. 14/067,167
Executed on: October 23, 2013	

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd, of No.8, Li-Hsin Road. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. hereinafter referred to as ASSIGNEES, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

TSMC2013-0836/0503-A38052US

ASSIGNMENT

Date

10/23 '13

Name: Chi-Cheng TSAI   (Last name: TSAI)

Chi-Cheng Tsai

Date

9/23 '13

Name: Hung-Chi WU   (Last name: WU)

Hung-chi WU

Date

10/23 '13

Name: Tsung-Chuan LEE   (Last name: LEE)

Tsung-Chuan Lee

Date

10/23 '13

Name: Chung-Hsien LIN   (Last name: LIN)

Chung-Hsien Lin